TestConX中国 China

征稿启事 TestConX 中国 2024

TestConX 中国 2024 线下研讨会， 2024 年 10 月 31 日（**周四**）

诚邀您参加第 10 届电子测试技术研讨会 TestConX China，将于 2024 年 10 月 31 日（周四）以**线下**活动的形式在上海举办。届时将举行为期一天的技术主题演讲和一个 TestConX Expo 线下交流展，您将在那发现最新的测试技术、相关产品和解决方案。我们聚焦于电子行业的测试领域，提供从人员到解决方案的交流对接，千万别错过本届的行业盛会！

TestConX 中国技术委员会诚邀业内优秀人士来稿，尤其是 5G 无线测试的挑战和解决方案相关演讲稿，包括超高容量与毫米波技术。关于老化及其他宽泛的测试主题征稿也将受到高度重视。

TestConX 的每场演讲时长保持在 30 分钟（25 分钟主题演讲，5 分钟听众互动问答）。作者可以选择以中文或英语演讲，并只需准备一份 PPT 即可（无需提前编写文章）。

请于 2024 年 7 月 12 日前提交您（原创或未曾发表的演讲）的 250 到 500 字的主题摘要。

请通过以下方式提交：

- 在线填表 https://testconx.org/china-abstracts
- 或者发送电子邮件至 china-abstracts@testconx.org ，包括演示文稿的标题，每位作者的完整联系信息（姓名，所属机构/公司名称，职位，电子邮件地址，电话号码和邮寄地址）以及演示者姓名。

我们将对摘要进行审核并在 2024 年 8 月 2 日左右通知到作者。

演讲稿提交截止日期为 2024 年 9 月 30 日。

来稿语言：英语或中文。PPT 以英语为主，采用 TestConX 提供的模版编写，可以选择中文对照。

特此 TestConX 组委会诚挚邀请业内优秀人士踊跃来稿！

初次来稿请提供 250 至 500 字的演讲摘要（内容原创且之前未发表，PPT 演讲材料即可，无需提供完整文章）、演讲标题、演讲者及作者完整信息（所有作者姓名，工作单位，职务，电子邮箱，电话，邮寄地址）。

最感兴趣的封装测试应用领域包括：

- 机器学习/人工智能
  - 采用机器学习/人工智能方式测试，应用于 ASIC 芯片
  - 机器学习/人工智能在测试过程和测试数据中的应用
- 航空航天 – 高可靠性及极端温度测试
- 智能手机及 5G 包括 AiP 天线封装及毫米波技术
- 精细间距(<150μm)晶圆级芯片尺寸封装
- 图像传感器
- 微机电系统（MEMS）传感器和物联网

其他感兴趣的范畴包括以下报告主题（不局限于此）：

封装测试中的电气和机械方面挑战

- 包括 5G 和毫米波在内的高频和高数据率技术晶圆级封装 (WLP) 和面板级处理 (PLP)
- 高电流、高功率和/或高温设备测试处理器和更换套件设计及考虑因素精密间距开尔文接触
- 热量管理与建模
- 接插技术
- 裸片，片上系统(SOC),系统级封装(SiP)及 2D/2.5D/3D 封装测试
- 用于良好裸晶(KGD) 或终检的晶圆级芯片规模测试 (WLCSP)

测试进程和操作上的挑战

- 片上级天线封装测试（OTA、AiP）
- 系统级测试(SLT)
- 老化测试的操作
- 接插件修复，清洗及重新电镀方法
- 大规模并行及非单一测试(晶圆级和面板级)
- 减少认证测试和生产时间的策略
- 接插件与 PCB 验证，检查和鉴定
- 条带测试和托盘内测试对任务关键和医疗应用的高可靠性测试微机电系统 (MEMS) 和非电气 (声、光、磁、流体, 等.) 模拟测试
- 启动、表征和验证
- 云与大数据分析
- 可测试性设计，包括 ATE 测试、SLT 和可靠性测试
- 故障分析

模块和产品测试上的挑战

- 治具与测试探针
- 电测自动化
- 物料的自动化处理
- 大规模和批量场景下的无线测试
- 热量控制

印刷线路板(PCB)设计和制造上的挑战

- 高温老化的场景应用
- 高数据速率测试应用
- 负载板和探针卡的空间变压器和超精细间距板间互联

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TestConX China 2024

Pudong, Shanghai October 31, 2024

Join us for the 10th annual TestConX China workshop to be held **in-person** on October 31, 2024. There will be a full day of technical presentation and a TestConX EXPO where you will find the latest in test products and solutions. *Don't miss the preeminent China event focused on connecting electronic test professionals to solutions.*

The TestConX China Technical Program Committee is seeking presentations that highlight the challenges and solutions for 5G wireless testing including ultra-high volume operations and millimeter-wave technology. Other proposals on a broad range of test and burn-in topics, as illustrated below, are also highly valued.

Each presentation at TestConX China is provided a thirty-minute presentation slot (approximately 25 minutes for the presentation with 5 minutes for questions and answers). Authors may choose to present in English or Mandarin. And authors only need to prepare a PowerPoint presentation. (There is no paper to write.)

Please submit a 250-to-500-word abstract for presentations of your original, previously unpublished, technical presentation by July 12, 2024.

Submit via:

• Online form https://testconx.org/china-abstracts

or

•Email china-abstracts@testconx.org including title of presentation, complete contact information (name, affiliation/company name, job title, email address, phone number, and mailing address) for each author, and name of presenter.

Abstracts will be reviewed and authors will be notified around August 2, 2024.

Presentation submissions are due September 30, 2024.

Language: Presentation in English or Mandarin. PowerPoint slides in English using the TestConX provided template with the option to also create Chinese slides.

Test applications of highest interest include:

- Machine Learning / Artificial Intelligence
  - Testing of ML/AI specific application specific integrated circuits (ASICs)

    - Application of ML/AI to test process and test data
- Electric vehicles - power, sensing, and battery test
- Aerospace - high realibility and extreme temperature testing
- Smartphone & 5G including antenna in package (AiP) and mm-wave
- Fine Pitch (< 150 µm) Wafer Level Chip Scale Packaging
- Image Sensors
- MEMS Sensors and Internet of Things

Topics that address the **challenges of these and other test applications** include, but are not limited to:

Electrical & Mechanical Challenges in package testing

- High frequency and high data rate techniques and technologies including 5G and mm-wave
- Wafer Level Packages (WLP) and Panel Level Processing (PLP)
- High current, high power, and/or high temperature device testing
- Handler & change kit designs and considerations
- Fine Pitch Kelvin Contacting
- Thermal management and modelling
- Contact technology
- Bare Die, system on a chip (SOC), system-in-package (SiP), and 2/2.5/3D package testing
- Wafer level chip scale (WLCSP) test for Known Good Die (KGD) or final test

Test Process & Operational Challenges

- Over the Air (OtA) and Antenna in Package (AiP) testing
- System Level Test (SLT)
- Test & Burn-in floor operations
- Socket repair, cleaning, and re-plating methods
- Massively parallel and non-singulated test (Wafer Level and Panel Level)
- Test strategies for reducing qualification and production time
- Socket & PCB verification, checkout, & qualification
- Strip Testing and Test-in-Tray
- High reliability testing for mission critical and medical applications
- Microelectromechanical system (MEMS) and non-electrical (optical, fluidic, magnetic, acoustic, etc.) stimuli testing
- Bring-up, characterization, and validation
- Cloud and big-data analytics
- Design for testability including ATE test, SLT, and reliability test
- Failure analysis

Module & Product Test Challenges

- Fixturing and test contact
- Test automation
- Automated material handling
- Wireless testing at scale / high volume
- Thermal control

Printed Circuit Board (PCB) Design & Manufacturing Challenges

- For high temperature Burn-in board applications
- High data rate test applications
- Space Transformers and Ultra-fine pitch for load boards and probe cards
- Board to Board Interconnects

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